ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATIONAL AND PARTY	PC, Bannockl	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a decla the declaratio	ration of th n encompa	e substances asses all lowe	within the r r level mate	nanufacturer rials for whi	r listed iter ch the mar	n. Note: if	the item is an as has engineering	sembly with lowe responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information				
Supplier Information															
Company name*	Company un	Company unique ID			Unique ID Authority					Response Date*					
onsemi											2025-05-12				
Contact Name Ti			Title - Contact			Phone - Contact*					Email - Contact*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Authorized Representative* Title -			Title - Representative			Phone - Representative*				1	Email - Representative*				
Product-Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item	n Number	Mfr Item Name Low-Side Gate Driver SO8			Effective D	ate Versi	ion	Manufacturing Site		We	ight*	UOM	Unit Type	
	FAN326	68TMX-F085			2025-05-12 TH2		ГН2	80.792		792	mg	Each			
Manufacturing Proccess Informa	tion												·		
Terminal Plating / Grid Array Ma	aterial 7	Ferminal Base A	Alloy	J-STD-020 MS	L Rating	Peak Process Body T		y Temperatu	perature Max Time at Peak		Temperature Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 3		3		260		C	30		seconds	3			
Comments															
TTENTION: MSL 3 Rated item require	s Bake and L	Dry Pack (after	electrical test)												
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.16	mg	Supplier	Silicon (Si)	7440-21-3		2.16	mg
Die Attach	1.144	mg		Bismaleimide Resin	proprietary data		0.1888	mg
			Supplier	Other Additive Agents	Proprietary Data		0.04	mg
			Supplier	Silver (Ag)	7440-22-4		0.9152	mg
Lead Frame	31.136	mg	Supplier	Zinc (Zn)	7440-66-6		0.0374	mg
			Supplier	Iron (Fe)	7439-89-6		0.7286	mg
			Supplier	Copper (Cu)	7440-50-8		30.3451	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0249	mg
Mold Compound-Black	45.29	mg		Epoxy resin	proprietary data		2.7174	mg
			Supplier	Phenolic Resin	Proprietary Data		2.7174	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2264	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.4965	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1322	mg
Plating	0.435	mg	Supplier	Palladium (Pd)	7440-05-3		0.0173	mg
			В	Nickel (Ni)	7440-02-0		0.4074	mg
			Supplier	Gold (Au)	7440-57-5		0.0104	mg
Wire Bond - Au	0.627	mg	Supplier	Gold (Au)	7440-57-5		0.627	mg